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Jameco Part Number 1338935p2

DATA SHEET

Family Specifications

January 1995

File under Integrated Circuits, IC04

Family Specifications

INTRODUCTION

These specifications cover the common electrical characteristics of the entire HE4000B family, unless otherwise specified in the individual device data sheet.

The LOCMOS HE4000B family devices will operate over a recommended V_{DD} power supply range of 3 to 15 V, as referenced to V_{SS} (usually ground). Parametric limits are guaranteed for V_{DD} of 5, 10 and 15 V. Because of the wide operating voltage, power supply regulation is less critical than with other types of logic. The lower limit of the supply voltage is 3 V, or as determined by required system speed and/or noise immunity or interface to other logic. The recommended upper limit is 15 V or as determined by power dissipation constraints or interface to other logic. Unused inputs must be connected to V_{DD} , V_{SS} or another input. Inputs and outputs are protected against electrostatic effects in a wide variety of device-handling situations. However, to be totally safe, it is desirable to take handling precautions into account.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{DD}	Supply voltage		-0.5	—	+18	V
V_I	Voltage on any input		-0.5	—	$V_{DD} + 0.5$	V
$\pm I$	DC current into any input or output		—	—	10	mA
P_{tot}	Power dissipation per package HEF (plastic and ceramic DIL)	$T_{amb} = -40$ to $+70$ °C $T_{amb} = +70$ to $+85$ °C	derate linearly with 12 mW/K		750	mW
	HEF (plastic SO mini-pack)	$T_{amb} = -40$ to $+70$ °C $T_{amb} = +70$ to $+85$ °C	derate linearly with 8 mW/K		500	mW
	HEC (ceramic DIL)	$T_{amb} = -55$ to $+70$ °C $T_{amb} = +70$ to $+125$ °C	derate linearly with 8 mW/K		500	mW
P	Power dissipation per output		—	—	100	mW
T_{stg}	Storage temperature		-65	—	+150	°C
T_{amb}	Operating ambient temperature (HEF)		-40	—	+85	°C
T_{amb}	Operating ambient temperature (HEC)		-55	—	+125	°C

DC CHARACTERISTICS FOR HEF $V_{SS} = 0$ V; for all devices unless otherwise specified.

SYMBOL	PARAMETER	V _{DD} (V)	T _{amb} (°C)						UNIT	CONDITIONS	
			−40		+25		+85				
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.			
I _{DD}	Quiescent device current										
	gates	5	–	1.0	–	1.0	–	7.5	μA	all valid input combinations; V _I = V _{SS} or V _{DD} ; I _O = 0	
		10	–	2.0	–	2.0	–	15.0			
		15	–	4.0	–	4.0	–	30.0			
	buffers, flip-flops	5	–	4.0	–	4.0	–	30			μA
		10	–	8.0	–	8.0	–	60			
		15	–	16.0	–	16.0	–	120			
	MSI	5	–	20	–	20	–	150			μA
		10	–	40	–	40	–	300			
		15	–	80	–	80	–	600			
	LSI	5	–	50	–	50	–	375			μA
		10	–	100	–	100	–	750			
		15	–	200	–	200	–	1500			
	V _{OL}	Output voltage LOW	5	–	0.05	–	0.05	–	0.05	V	V _I = V _{SS} or V _{DD} ; I _O < 1 μA
		10	–	0.05	–	0.05	–	0.05			
15		–	0.05	–	0.05	–	0.05				
V _{OH}	Output voltage HIGH	5	4.95	–	4.95	–	4.95	–	V	V _I = V _{SS} or V _{DD} ; I _O < 1 μA	
	10	9.95	–	9.95	–	9.95	–				
	15	14.95	–	14.95	–	14.95	–				
V _{IL}	Input voltage LOW (buffered stages only)	5	–	1.5	–	1.5	–	1.5	V	V _O = 0.5 V or 4.5 V; I _O < 1 μA	
	10	–	3.0	–	3.0	–	3.0	V _O = 1.0 V or 9.0 V; I _O < 1 μA			
	15	–	4.0	–	4.0	–	4.0	V _O = 1.5 V or 13.5 V; I _O < 1 μA			
V _{IH}	Input voltage HIGH (buffered stages only)	5	3.5	–	3.5	–	3.5	–	V	V _O = 0.5 V or 4.5 V; I _O < 1 μA	
	10	7.0	–	7.0	–	7.0	–	V _O = 1.0 V or 9.0 V; I _O < 1 μA			
	15	11.0	–	11.0	–	11.0	–	V _O = 1.5 V or 13.5 V; I _O < 1 μA			

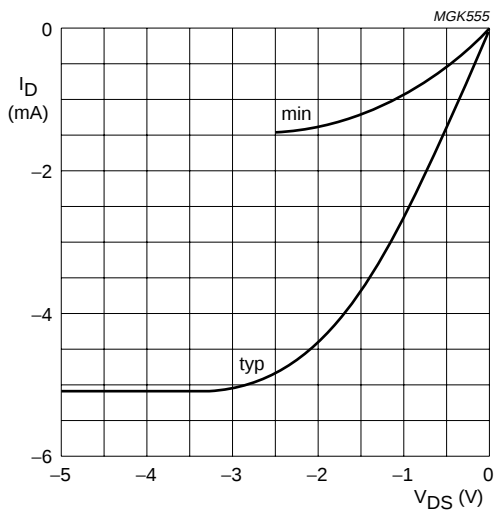
SYMBOL	PARAMETER	V _{DD} (V)	T _{amb} (°C)						UNIT	CONDITIONS
			−40		+25		+85			
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
V _{IL}	Input voltage LOW (unbuffered stages only)	5	−	1	−	1	−	1	V	V _O = 0.5 V or 4.5 V; I _O < 1 μA
		10	−	2	−	2	−	2		V _O = 1.0 V or 9.0 V; I _O < 1 μA
		15	−	2.5	−	2.5	−	2.5		V _O = 1.5 V or 13.5 V; I _O < 1 μA
V _{IH}	Input voltage HIGH (unbuffered stages only)	5	4	−	4	−	4	−	V	V _O = 0.5 V or 4.5 V; I _O < 1 μA
		10	8	−	8	−	8	−		V _O = 1.0 V or 9.0 V; I _O < 1 μA
		15	12.5	−	12.5	−	12.5	−		V _O = 1.5 V or 13.5 V; I _O < 1 μA
I _{OL}	Output (sink) current LOW	5	0.52	−	0.44	−	0.36	−	mA	V _O = 0.4 V; V _I = 0 or 5 V
		10	1.3	−	1.1	−	0.9	−		V _O = 0.5 V; V _I = 0 or 10 V
		15	3.6	−	3.0	−	2.4	−		V _O = 1.5 V; V _I = 0 or 15 V
−I _{OH}	Output (source) current HIGH	5	0.52	−	0.44	−	0.36	−	mA	V _O = 4.6 V; V _I = 0 or 5 V
		10	1.3	−	1.1	−	0.9	−		V _O = 9.5 V; V _I = 0 or 10 V
		15	3.6	−	3.0	−	2.4	−		V _O = 13.5 V; V _I = 0 or 15 V
−I _{OH}	Output (source) current HIGH	5	1.7	−	1.4	−	1.1	−	mA	V _O = 2.5 V; V _I = 0 or 5 V
± I _{IN}	Input leakage current	15	−	0.3	−	0.3	−	1.0	μA	V _I = 0 or 15 V
I _{OZH}	3-state output leakage current; HIGH	15	−	1.6	−	1.6	−	12.0	μA	output returned to V _{DD}
−I _{OZL}	3-state output leakage current; LOW	15	−	1.6	−	1.6	−	12.0	μA	output returned to V _{SS}

DC CHARACTERISTICS FOR HEC $V_{SS} = 0$ V; for all devices unless otherwise specified.

SYMBOL	PARAMETER	V _{DD} (V)	T _{amb} (°C)						UNIT	CONDITIONS		
			−55		+25		+125					
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.				
I _{DD}	Quiescent device current											
	gates	5	–	0.25	–	0.25	–	7.5	μA	all valid input combinations; V _I = V _{SS} or V _{DD} ; I _O = 0		
		10	–	0.5	–	0.5	–	15.0				
		15	–	1.0	–	1.0	–	30.0				
	buffers, flip-flops	5	–	1.0	–	1.0	–	30			μA	
		10	–	2.0	–	2.0	–	60				
		15	–	4.0	–	4.0	–	120				
	MSI	5	–	5.0	–	5.0	–	150			μA	
		10	–	10.0	–	10.0	–	300				
		15	–	20.0	–	20.0	–	600				
	LSI	5	–	15	–	15	–	375	μA			
		10	–	25	–	25	–	750				
		15	–	50	–	50	–	1500				
	V _{OL}	Output voltage LOW	5	–	0.05	–	0.05	–	0.05		V	V _I = V _{SS} or V _{DD} ; I _O < 1 μA
		10	–	0.05	–	0.05	–	0.05				
15		–	0.05	–	0.05	–	0.05					
V _{OH}	Output voltage HIGH	5	4.95	–	4.95	–	4.95	–	V	V _I = V _{SS} or V _{DD} ; I _O < 1 μA		
	10	9.95	–	9.95	–	9.95	–					
	15	14.95	–	14.95	–	14.95	–					
V _{IL}	Input voltage LOW (buffered stages only)	5	–	1.5	–	1.5	–	1.5	V	V _O = 0.5 V or 4.5 V; I _O < 1 μA		
	10	–	3.0	–	3.0	–	3.0	V _O = 1.0 V or 9.0 V; I _O < 1 μA				
	15	–	4.0	–	4.0	–	4.0	V _O = 1.5 V or 13.5 V; I _O < 1 μA				
V _{IH}	Input voltage HIGH (buffered stages only)	5	3.5	–	3.5	–	3.5	–	V	V _O = 0.5 V or 4.5 V; I _O < 1 μA		
	10	7.0	–	7.0	–	7.0	–	V _O = 1.0 V or 9.0 V; I _O < 1 μA				
	15	11.0	–	11.0	–	11.0	–	V _O = 1.5 V or 13.5 V; I _O < 1 μA				

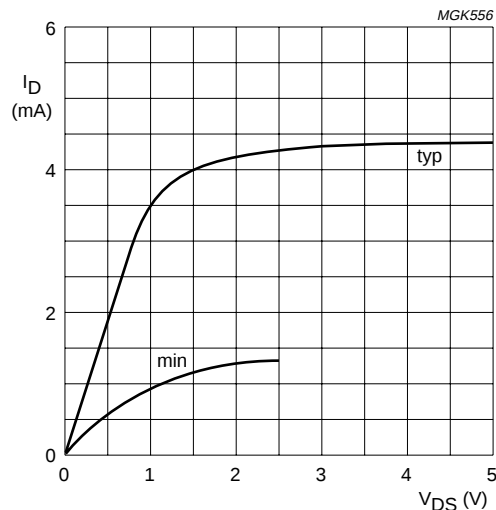
SYMBOL	PARAMETER	V _{DD} (V)	T _{amb} (°C)						UNIT	CONDITIONS
			−55		+25		+125			
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
V _{IL}	Input voltage LOW (unbuffered stages only)	5	–	1	–	1	–	1	V	V _O = 0.5 V or 4.5 V; I _O < 1 μA
		10	–	2	–	2	–	2		V _O = 1.0 V or 9.0 V; I _O < 1 μA
		15	–	2.5	–	2.5	–	2.5		V _O = 1.5 V or 13.5 V; I _O < 1 μA
V _{IH}	Input voltage HIGH (unbuffered stages only)	5	4	–	4	–	4	–	V	V _O = 0.5 V or 4.5 V; I _O < 1 μA
		10	8	–	8	–	8	–		V _O = 1.0 V or 9.0 V; I _O < 1 μA
		15	12.5	–	12.5	–	12.5	–		V _O = 1.5 V or 13.5 V; I _O < 1 μA
I _{OL}	Output (sink) current LOW	5	0.64	–	0.5	–	0.36	–	mA	V _O = 0.4 V; V _I = 0 or 5 V
		10	1.6	–	1.3	–	0.9	–		V _O = 0.5 V; V _I = 0 or 10 V
		15	4.2	–	3.4	–	2.4	–		V _O = 1.5 V; V _I = 0 or 15 V
−I _{OH}	Output (source) current HIGH	5	0.64	–	0.5	–	0.36	–	mA	V _O = 4.6 V; V _I = 0 or 5 V
		10	1.6	–	1.3	–	0.9	–		V _O = 9.5 V; V _I = 0 or 10 V
		15	4.2	–	3.4	–	2.4	–		V _O = 13.5 V; V _I = 0 or 15 V
−I _{OH}	Output (source) current HIGH	5	1.7	–	1.4	–	1.1	–	mA	V _O = 2.5 V; V _I = 0 or 5 V
± I _{IN}	Input leakage current	15	–	0.1	–	0.1	–	1.0	μA	V _I = 0 or 15 V
I _{OZH}	3-state output leakage current; HIGH	15	–	0.4	–	0.4	–	12.0	μA	output returned to V _{DD}
−I _{OZL}	3-state output leakage current; LOW	15	–	0.4	–	0.4	–	12.0	μA	output returned to V _{SS}

Family Specifications



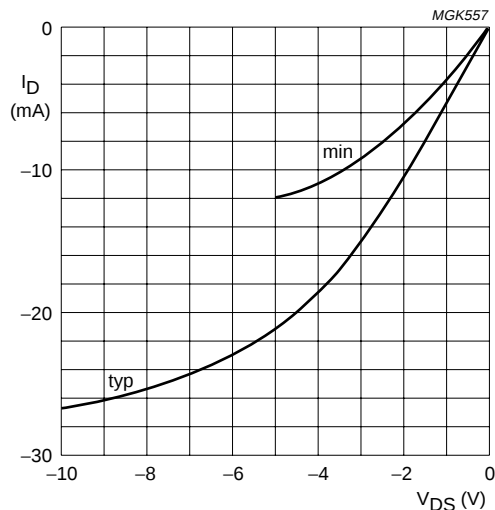
$V_{DD} = 5$ V; $T_{amb} = 25$ °C

Fig.1 P-channel drain characteristics (source).



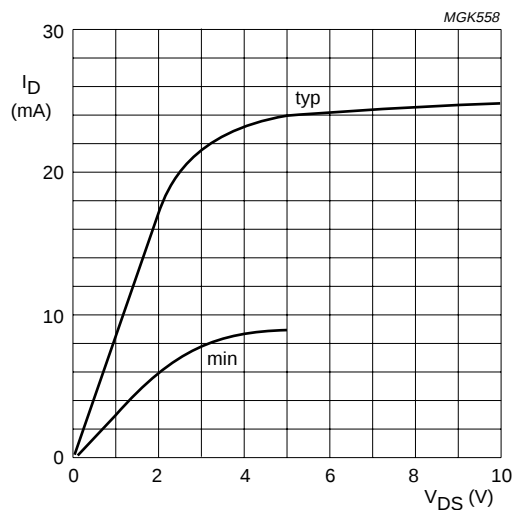
$V_{DD} = 5$ V; $T_{amb} = 25$ °C

Fig.2 N-channel drain characteristics (sink).



$V_{DD} = 10$ V; $T_{amb} = 25$ °C

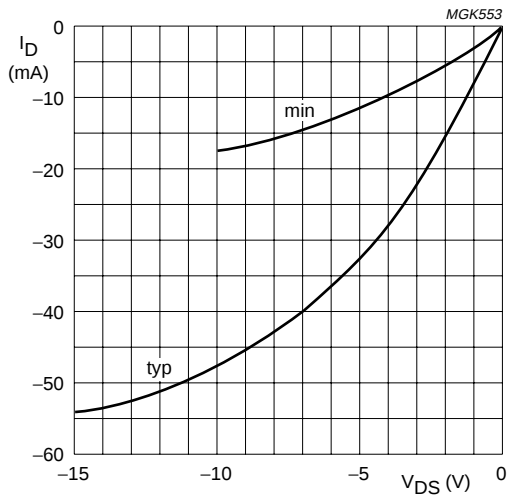
Fig.3 P-channel drain characteristics (source).



$V_{DD} = 10$ V; $T_{amb} = 25$ °C

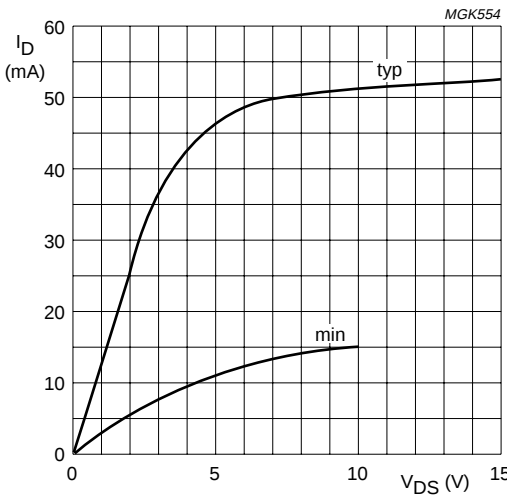
Fig.4 N-channel drain characteristics (sink).

Family Specifications



$V_{DD} = 15\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig.5 P-channel drain characteristics (source).



$V_{DD} = 15\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig.6 N-channel drain characteristics (sink).

Note: temperature coefficient: $-0.4\%/^{\circ}\text{C}$

Family Specifications

AC CHARACTERISTICS

Clock input rise and fall times (t_r , t_f)

The upper limits on t_r and t_f vary widely from device to device and with supply voltage. Unless otherwise specified in the individual data sheets it is recommended that input rise and fall times be less than 15 μ s for $V_{DD} = 5$ V; 4 μ s for $V_{DD} = 10$ V; 1 μ s for $V_{DD} = 15$ V.

Output transition times (t_{TLH} , t_{THL})

$V_{SS} = 0$; $T_{amb} = 25$ °C; $C_L = 50$ pF; input transition times ≤ 20 ns.

SYMBOL	PARAMETER	V_{DD} (V)	MIN.	TYP.	MAX.	UNIT	TYPICAL EXTRAPOLATION FORMULA
	output transition times						
t_{THL}	HIGH to LOW	5		60	120	ns	10 ns + (1.0 ns/pF) C_L
		10		30	60	ns	9 ns + (0.42 ns/pF) C_L
		15		20	40	ns	6 ns + (0.28 ns/pF) C_L
t_{TLH}	LOW to HIGH	5		60	120	ns	10 ns + (1.0 ns/pF) C_L
		10		30	60	ns	9 ns + (0.42 ns/pF) C_L
		15		20	40	ns	6 ns + (0.28 ns/pF) C_L

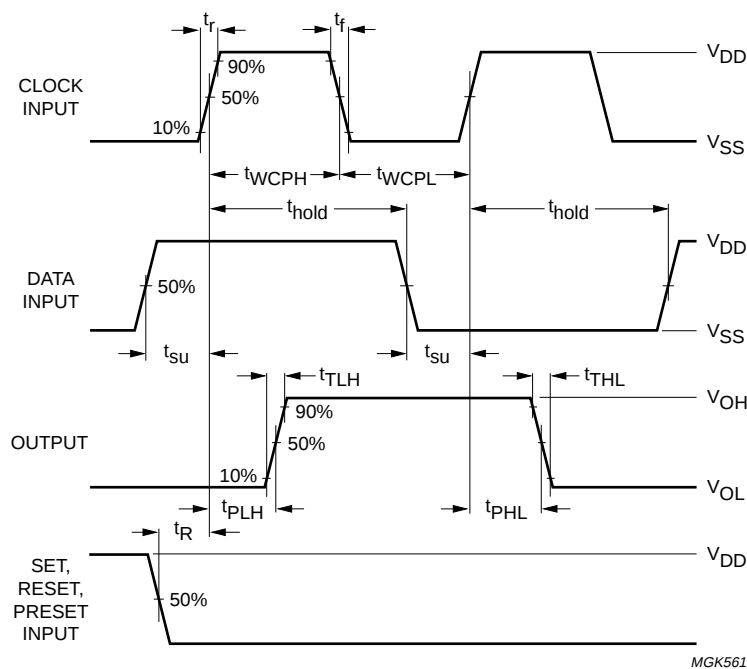
Temperature coefficient (typical values)

Propagation delays +0.35%/°C

Output transition times +0.35%/°C

Input capacitance (digital inputs)

Maximum input capacitance $C_I = 7.5$ pF



In the waveforms above the active transition of the clock input is going from LOW to HIGH and the active level of the forcing signals (SET, CLEAR and PRESET) is HIGH.

The actual direction of the active transition of the clock input and the actual active levels of the forcing signals are specified in the individual device data sheet.

Fig.7 Set-up times, hold times, recovery times and propagation delays for sequential logic circuits.

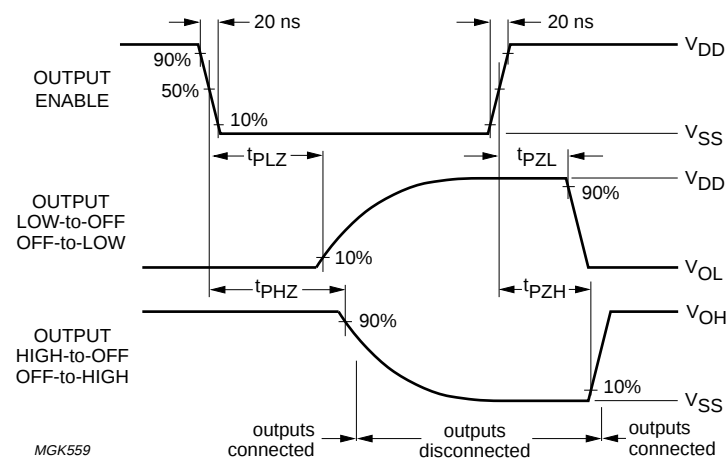


Fig.8 Propagation delays of 3-state outputs.

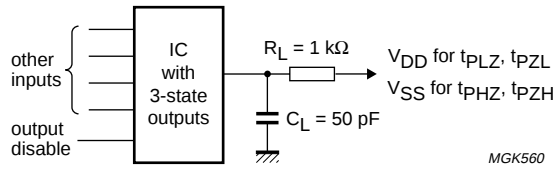


Fig.9 Test circuit of 3-state output ICs.

DEFINITIONS OF SYMBOLS AND TERMS USED IN DATA SHEETS

Currents

Positive current is defined as conventional current flow into a device.

Negative current is defined as conventional current flow out of a device.

I_{IN}	Input current; the current flowing into a device at specified input voltage and V_{DD} .
I_{OH}	Output current HIGH; the drive current flowing out of a device at specified HIGH output voltage and V_{DD} .
I_{OL}	Output current LOW; the drive current flowing into a device at specified LOW output voltage and V_{DD} .
I_{DD}	Quiescent power supply current; the current flowing into the V_{DD} lead at specified input and V_{DD} conditions.
I_{OZ}	Output OFF current; the leakage current flowing into or out of the output of a 3-state device in the OFF state when the output is connected to V_{DD} or V_{SS} .
I_{IL}	Input current LOW; the current flowing into a device at a specified LOW level input voltage and a specified V_{DD} .
I_{IH}	Input current HIGH; the current flowing into a device at a specified HIGH level input voltage and a specified V_{DD} .
I_{DDL}	Quiescent power supply current LOW; the current flowing into the V_{DD} lead with a specified LOW level input voltage on all inputs and specified V_{DD} conditions.
I_{DDH}	Quiescent power supply current HIGH; the current flowing into the V_{DD} lead with a specified HIGH level input voltage on all inputs and specified V_{DD} conditions.
I_Z	OFF state leakage current; the leakage current flowing into the output of a 3-state device in the OFF state at a specified output voltage and V_{DD} .

Voltages

All voltages are referenced to V_{SS} , which is the most negative potential applied to the device.

V_{DD}	Supply voltage; the most positive potential on the device.
V_{SS}	Supply voltage; for a device with a single negative power supply, the most negative power supply, used as the reference level for other voltages; typically ground.
V_{EE}	Supply voltage; one of two (V_{SS} and V_{EE}) negative power supplies. For a device with dual negative power supply, the most negative power supply as a reference level for other voltages.
V_{IH}	Input voltage HIGH; the range of input voltages that represents a logic HIGH level in the system.
V_{IL}	Input voltage LOW; the range of input voltages that represents a logic LOW level in the system.
V_{OH}	Output voltage HIGH; the range of voltages at an output terminal with a specified output loading and supply voltage. Device inputs are conditioned to establish a HIGH level at the output.
V_{OL}	Output voltage LOW; the range of voltages at an output terminal with a specified output loading and supply voltage. Device inputs are conditioned to establish a LOW level at the output.
V_P	Trigger threshold voltage; positive-going signal.
V_N	Trigger threshold voltage; negative-going signal.

Analogue terms

R_{ON}	ON resistance; the effective ON state resistance of an analogue transmission gate, at specified input voltage, output load and V_{DD} .
ΔR_{ON}	Δ ON resistance; the difference in effective ON resistance between any two transmission gates of an analogue device at specified input voltage, output load and V_{DD} .

AC switching parameters

f_i	Input frequency; for combinatorial logic devices the maximum number of inputs and outputs switching in accordance with the device truth table. For sequential logic devices the clock frequency using alternate HIGH and LOW for data input or using the toggle mode, whichever is applicable.	t_{su}	Set-up time; the interval immediately preceding the active transition of the timing pulse (usually the clock pulse) or preceding the transition of the control input to its latching level, during which interval the data to be recognized must be maintained at the input to ensure their recognition. A negative set-up time indicates that the correct logic level may be initiated sometime after the active transition of the timing pulse and still be recognized.
f_o	Output frequency; each output.	t_{PHZ}	3-state output disable time, HIGH to Z; the time between the specified reference points, normally the 50% point on the output enable input voltage waveform and a point representing a 0.1 V_{OH} drop on the output voltage waveform of a 3-state device, with the output changing from the output HIGH level (V_{OH}) to a high impedance OFF-state.
f_{max}	Clock frequency; clock input waveform should have a 50% duty cycle and be such as to cause the outputs to be switching from 10% V_{DD} to 90% V_{DD} in accordance with the device truth table.	t_{PLZ}	3-state output disable time, LOW to Z; the time between the specified reference points, normally the 50% point on the output enable input voltage waveform and a point representing a 0.1 ($V_{DD} - V_{OL}$) rise on the output voltage waveform of a 3-state device, with the output changing from the output LOW level (V_{OL}) to a high impedance OFF-state.
t_r, t_f	Clock input rise and fall times; 10% and 90% value.	t_{PZH}	3-state output enable time, Z to HIGH; the time between the specified reference points, normally the 50% point on the output enable input voltage waveform and a point representing a 0.1 V_{OH} rise on the output voltage waveform of a 3-state device, with the output changing from a high impedance OFF-state to the output HIGH level (V_{OH}).
t_{PLH}	Propagation delay time; the time between the specified reference points, normally the 50% points on the input and output waveforms, with the output changing from the defined LOW level to the defined HIGH level.	t_{PZL}	3-state output enable time, Z to LOW; the time between the specified reference points, normally the 50% point on the output enable input voltage waveform and a point representing a 0.1 ($V_{DD} - V_{OL}$) voltage drop on the output voltage waveform of a 3-state device, with the output changing from a high impedance OFF-state to the output LOW level (V_{OL}).
t_{PHL}	Propagation delay time; the time between the specified reference points, normally the 50% points on the input and output waveforms, with the output changing from the defined HIGH level to the defined LOW level.	t_R	Recovery time; the time between the end of an overriding asynchronous input, typically a clear or reset input, and the earliest permissible beginning of a synchronous control input, typically a clock input, normally measured at 50% points on both input voltage waveforms.
t_{TLH}	Transition time, LOW-to-HIGH; the time between two specified reference points on a waveform, normally 10% and 90% points, that is changing from LOW to HIGH.		
t_{THL}	Transition time, HIGH-to-LOW; the time between two specified reference points on a waveform, normally 90% and 10% points, that is changing from HIGH to LOW.		
t_W	Pulse width; the time between the 50% amplitude points on the leading and trailing edges of a pulse.		
t_{hold}	Hold time; the interval immediately following the active transition of the timing pulse (usually the clock pulse) or following the transition of the control input to its latching level, during which interval the data to be recognized must be maintained at the input to ensure their continued recognition. A negative hold time indicates that the correct logic level may be released prior to the timing pulse and still be recognized.		

DATA SHEET

Package outlines
Package information

January 1995

File under Integrated Circuits, IC04

Package information

Package outlines

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PACKAGE VERSIONS	DESCRIPTION	PAGE
SO		
SOT108-1	plastic small outline package; 14 leads; body width 3.9 mm	3
SOT109-1	plastic small outline package; 16 leads; body width 3.9 mm	4
SOT162-1	plastic small outline package; 16 leads; body width 7.5 mm	5
SOT163-1	plastic small outline package; 20 leads; body width 7.5 mm	6
SOT137-1	plastic small outline package; 24 leads; body width 7.5 mm	7
SOT136-1	plastic small outline package; 28 leads; body width 7.5 mm	8
SSOP		
SOT337-1	plastic shrink small outline package; 14 leads; body width 5.3 mm	9
SOT338-1	plastic shrink small outline package; 16 leads; body width 5.3 mm	10
SOT339-1	plastic shrink small outline package; 20 leads; body width 5.3 mm	11
SOT340-1	plastic shrink small outline package; 24 leads; body width 5.3 mm	12
SOT341-1	plastic shrink small outline package; 28 leads; body width 5.3 mm	13
DIP		
SOT27-1	plastic dual in-line package; 14 leads (300 mil)	14
SOT38-1 ⁽¹⁾	plastic dual in-line package; 16 leads (300 mil); long body	15
SOT102-1	plastic dual in-line package; 18 leads (300 mil)	16
SOT146-1	plastic dual in-line package; 20 leads (300 mil)	17
SOT101-1	plastic dual in-line package; 24 leads (600 mil)	18
SOT117-1	plastic dual in-line package; 28 leads (600 mil)	19
SOT129-1	plastic dual in-line package; 40 leads (600 mil)	20
CDIP		
SOT73-1	ceramic dual in-line package; 14 leads; glass seal	21
SOT74-1	ceramic dual in-line package; 16 leads; glass seal	22
SOT133-1	ceramic dual in-line package; 18 leads; glass seal	23
SOT152-2	ceramic dual in-line package; 20 leads; glass seal	24
SOT94-1	ceramic dual in-line package; 24 leads; glass seal	25
SOT135-1	ceramic dual in-line package; 28 leads; glass seal	26

Note

1. Corrected 26 June 1997.

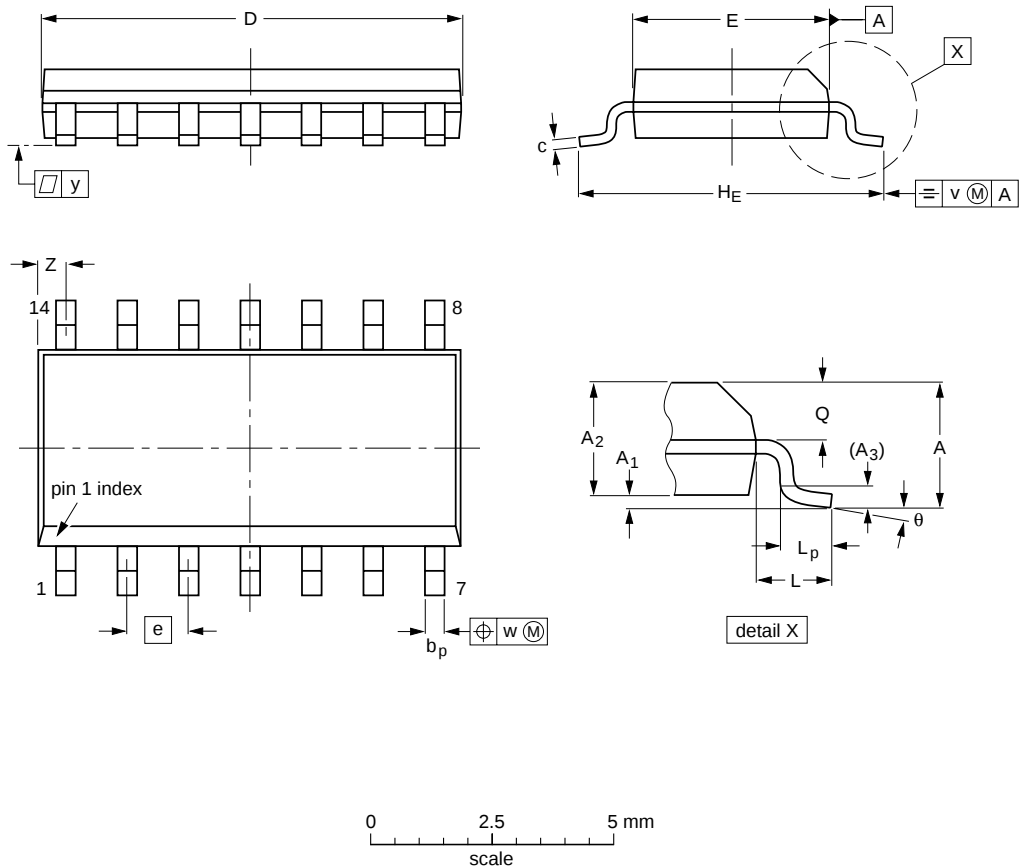
Package information

Package outlines

SO

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

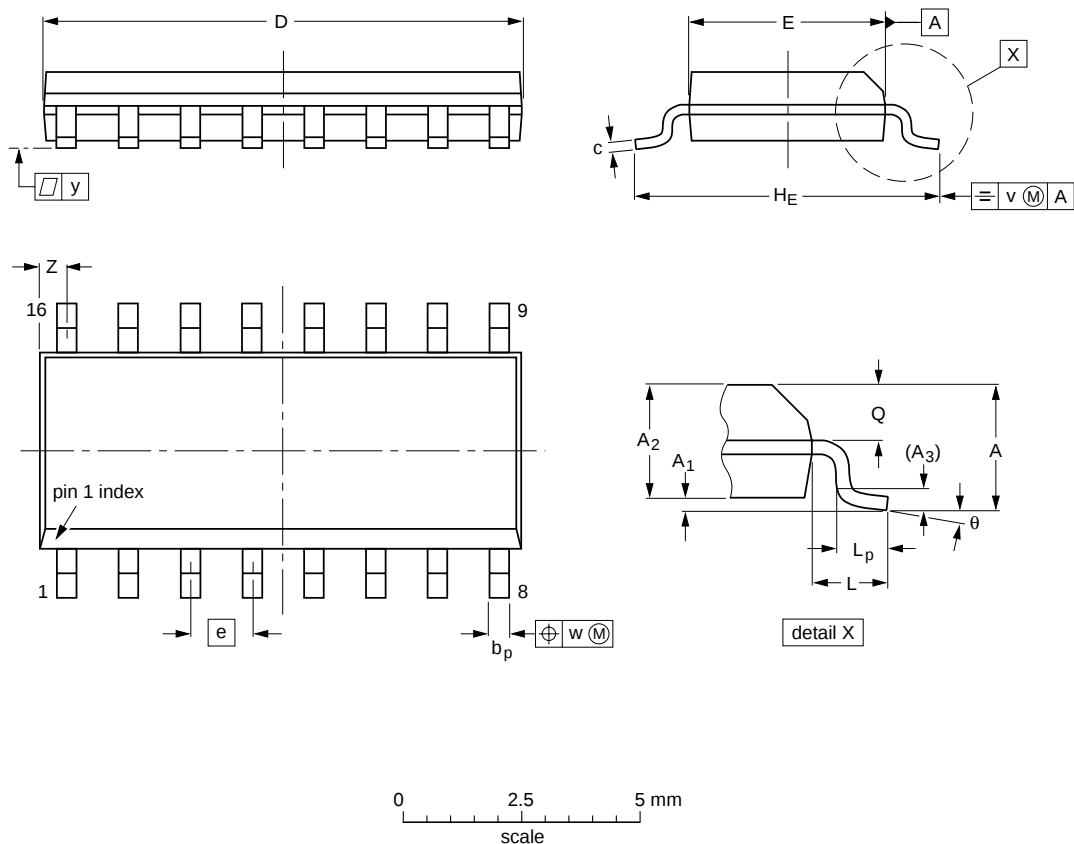
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06S	MS-012AB				95-01-23 97-05-22

Package information

Package outlines

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

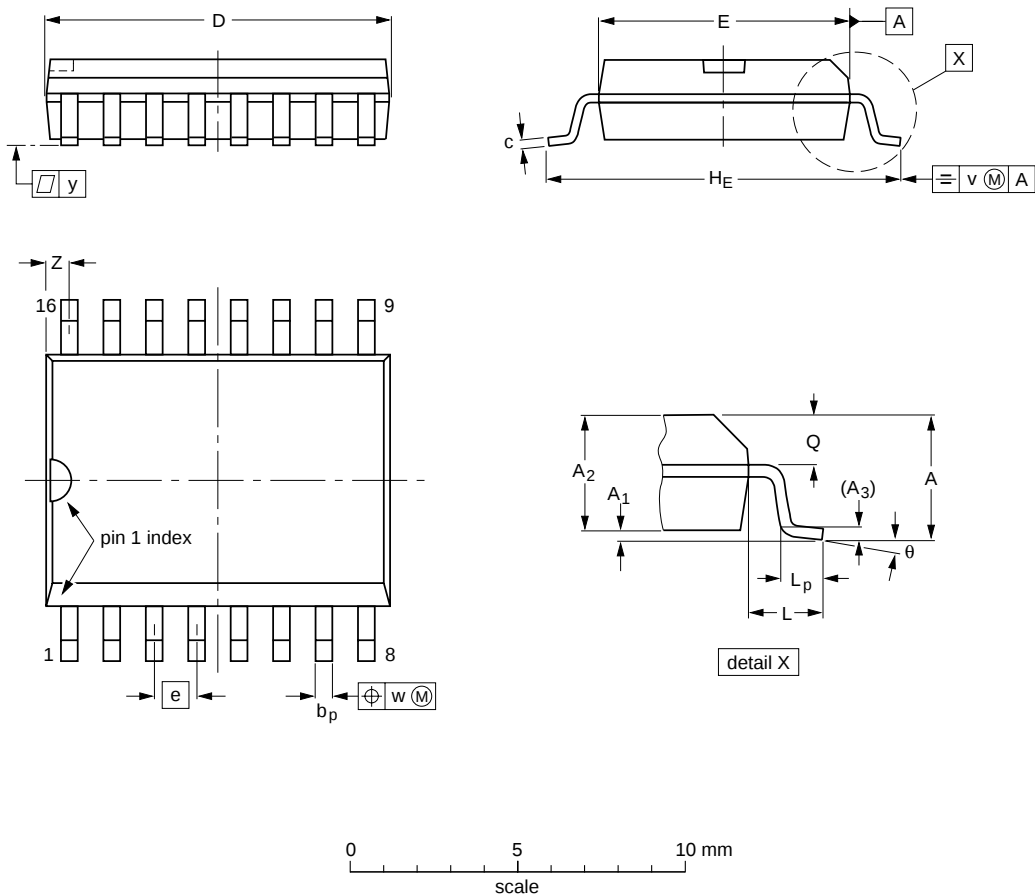
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07S	MS-012AC				95-01-23 97-05-22

Package information

Package outlines

SO16: plastic small outline package; 16 leads; body width 7.5 mm

SOT162-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

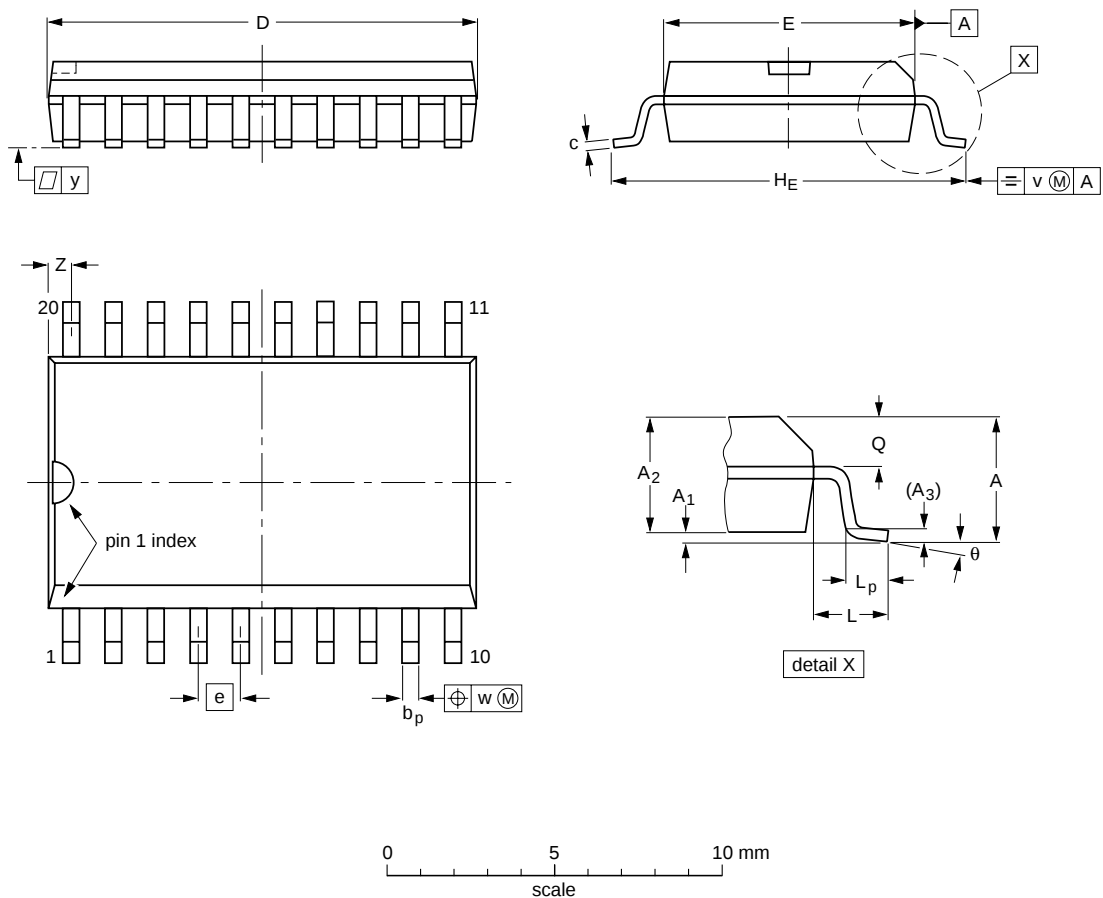
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT162-1	075E03	MS-013AA				95-01-24 97-05-22

Package information

Package outlines

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

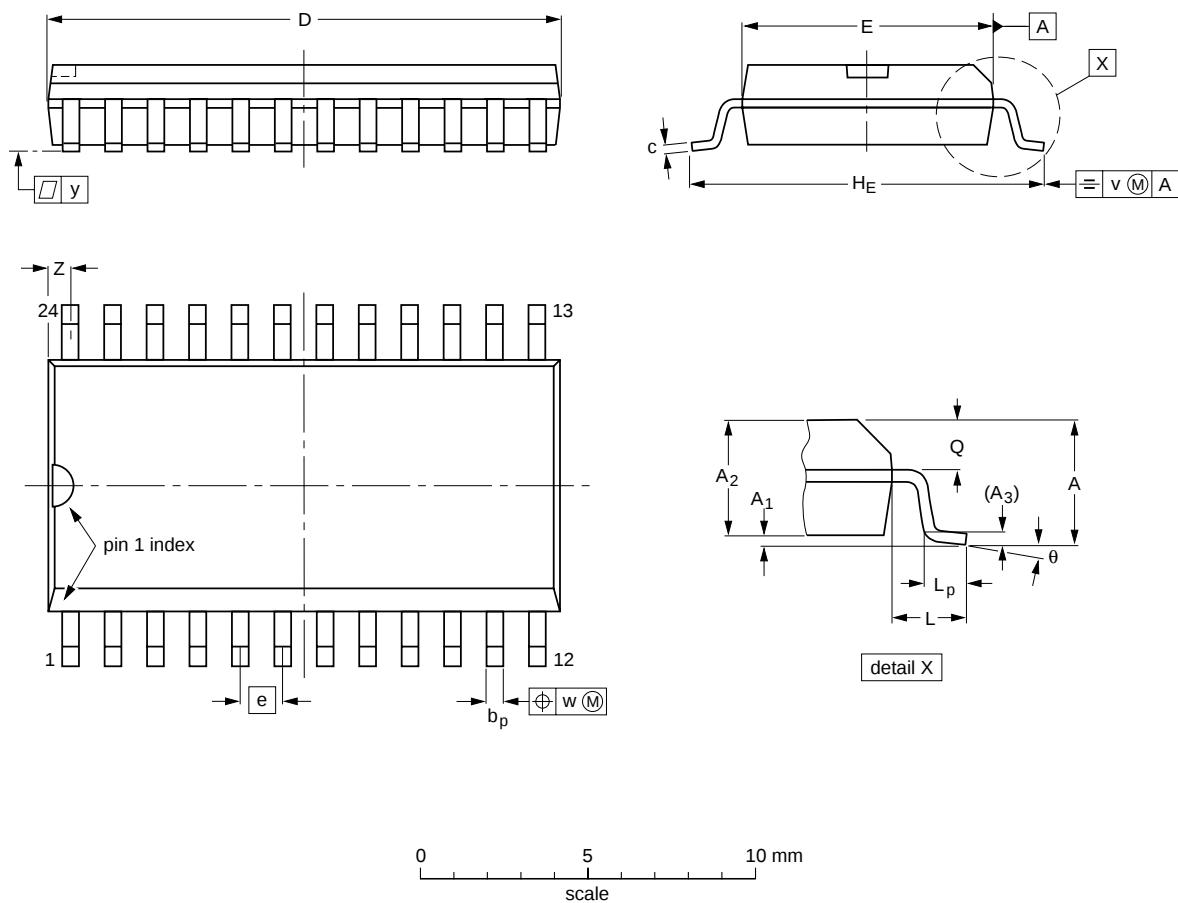
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				95-01-24 97-05-22

Package information

Package outlines

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

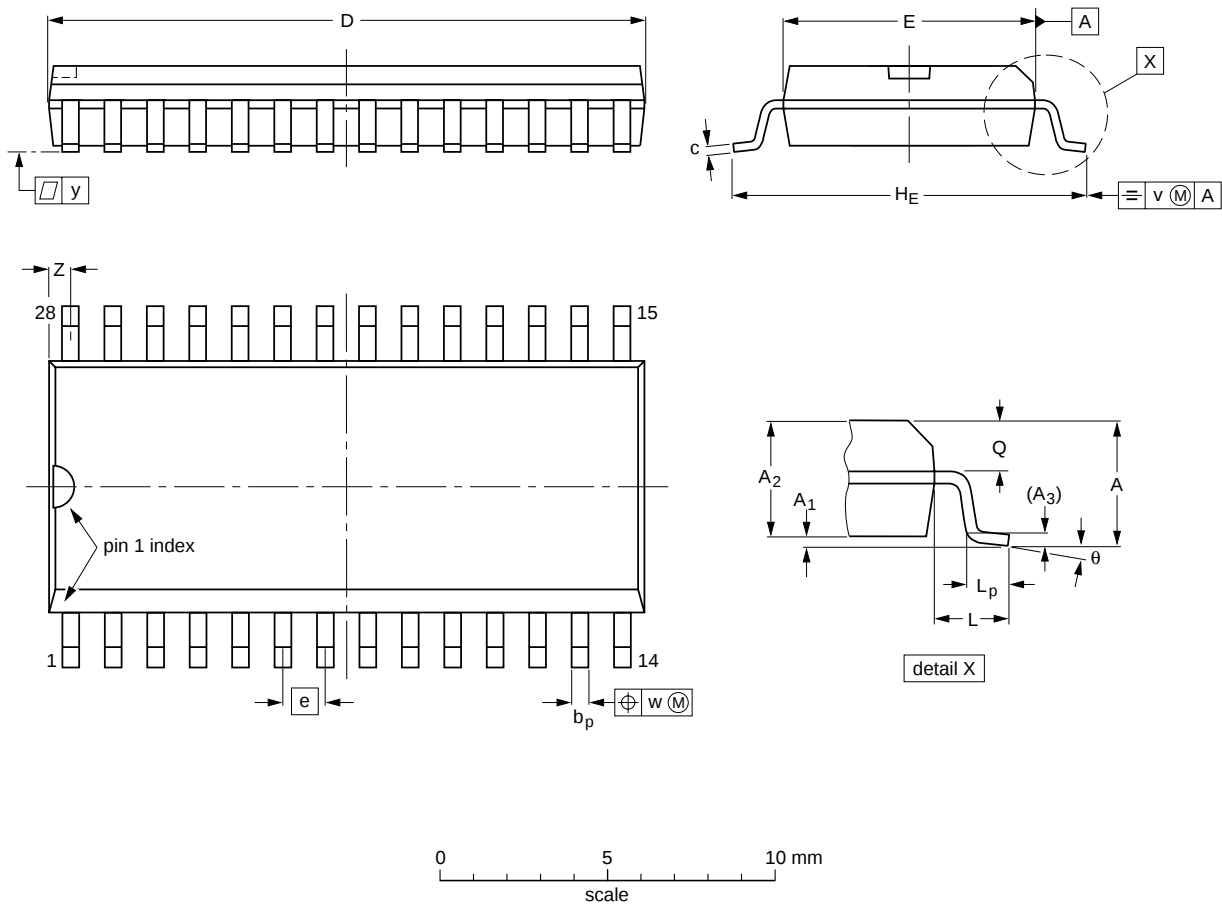
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT137-1	075E05	MS-013AD				95-01-24 97-05-22

Package information

Package outlines

SO28: plastic small outline package; 28 leads; body width 7.5 mm

SOT136-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	18.1 17.7	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.71 0.69	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT136-1	075E06	MS-013AE				95-01-24 97-05-22

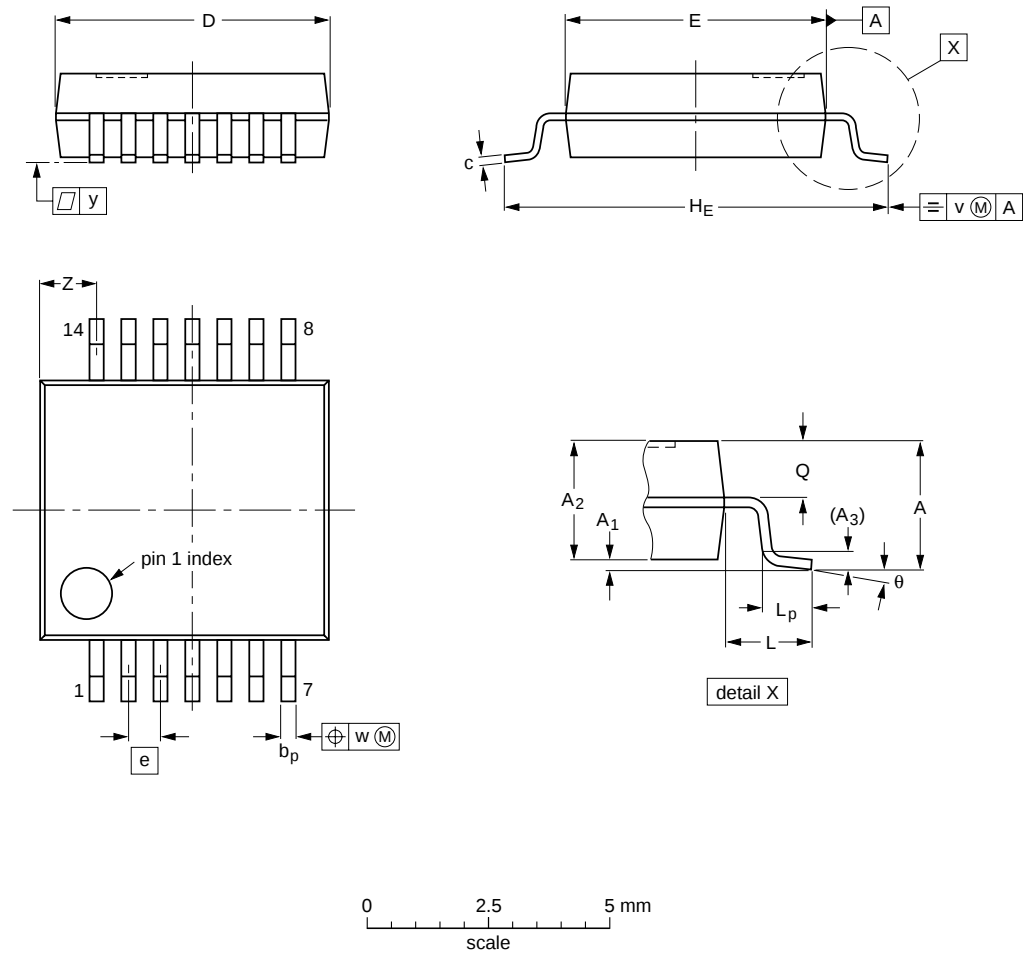
Package information

Package outlines

SSOP

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max.}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

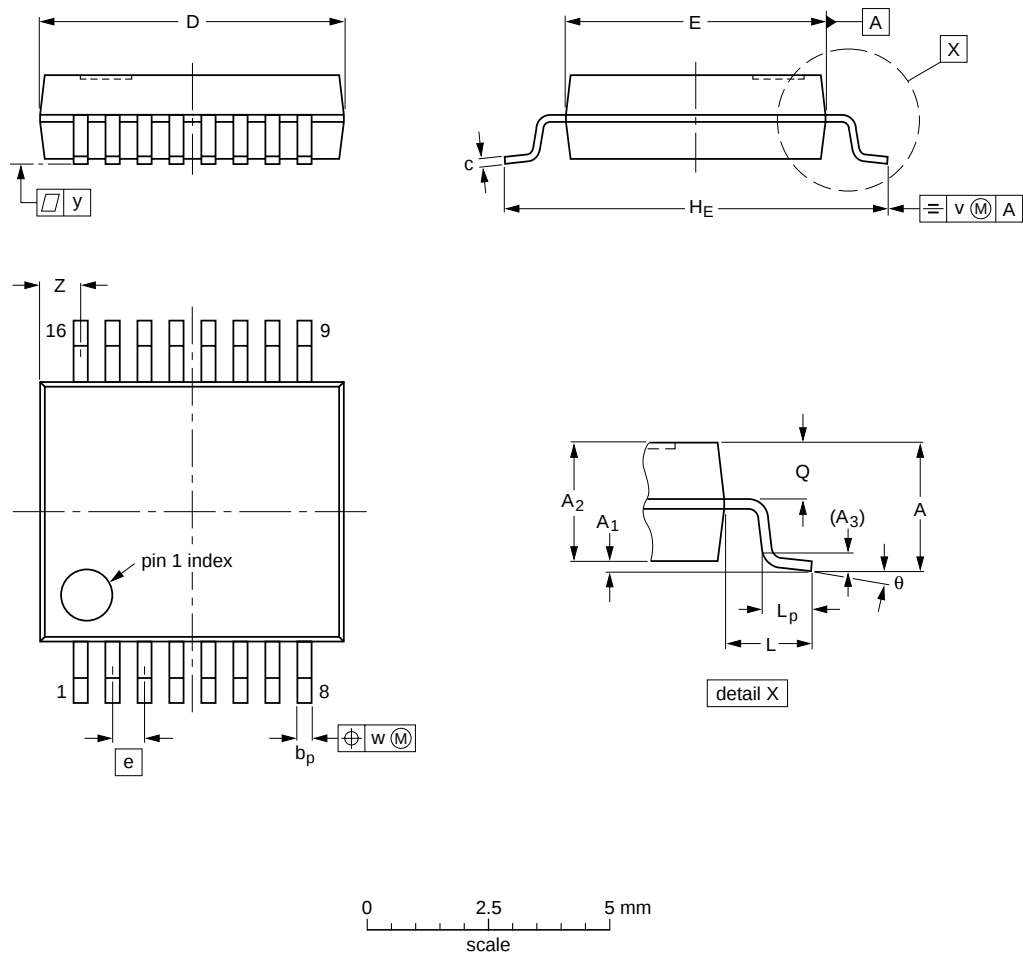
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT337-1		MO-150AB				95-02-04 96-01-18

Package information

Package outlines

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max.}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.00 0.55	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

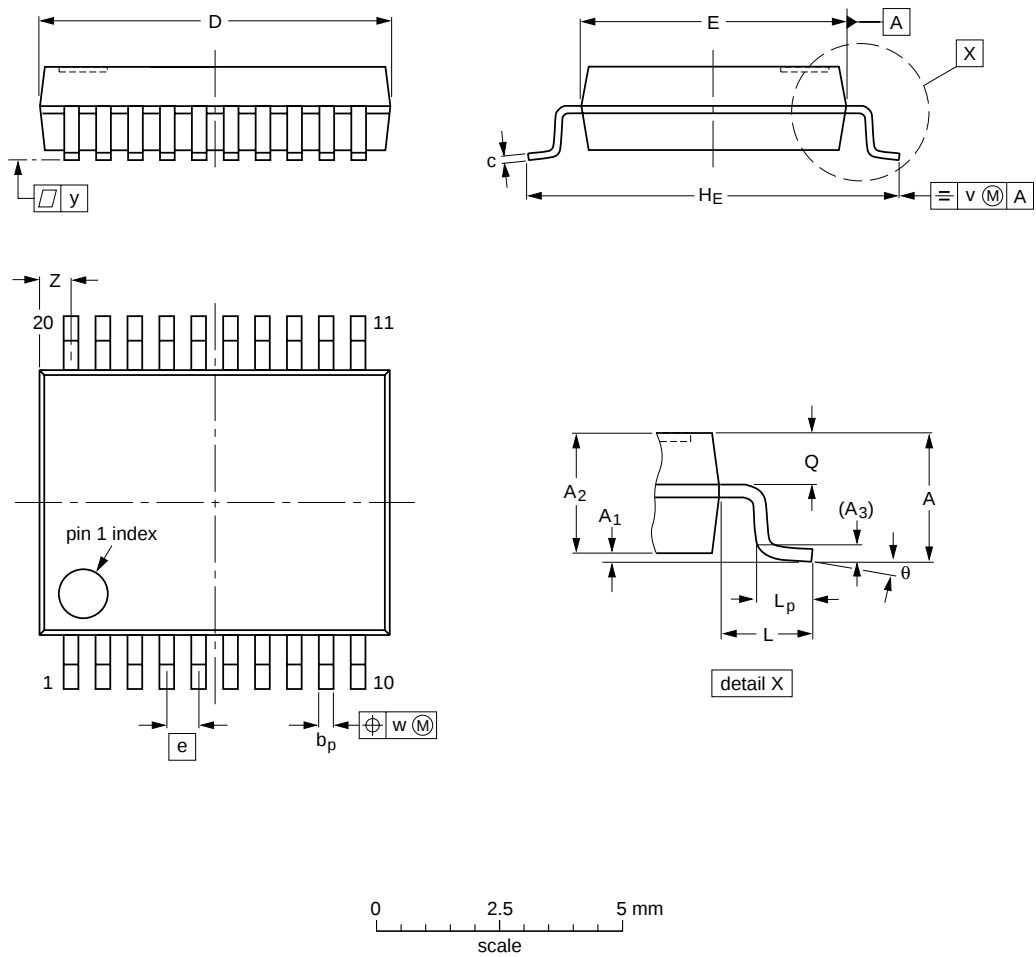
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT338-1		MO-150AC				94-01-14- 95-02-04

Package information

Package outlines

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

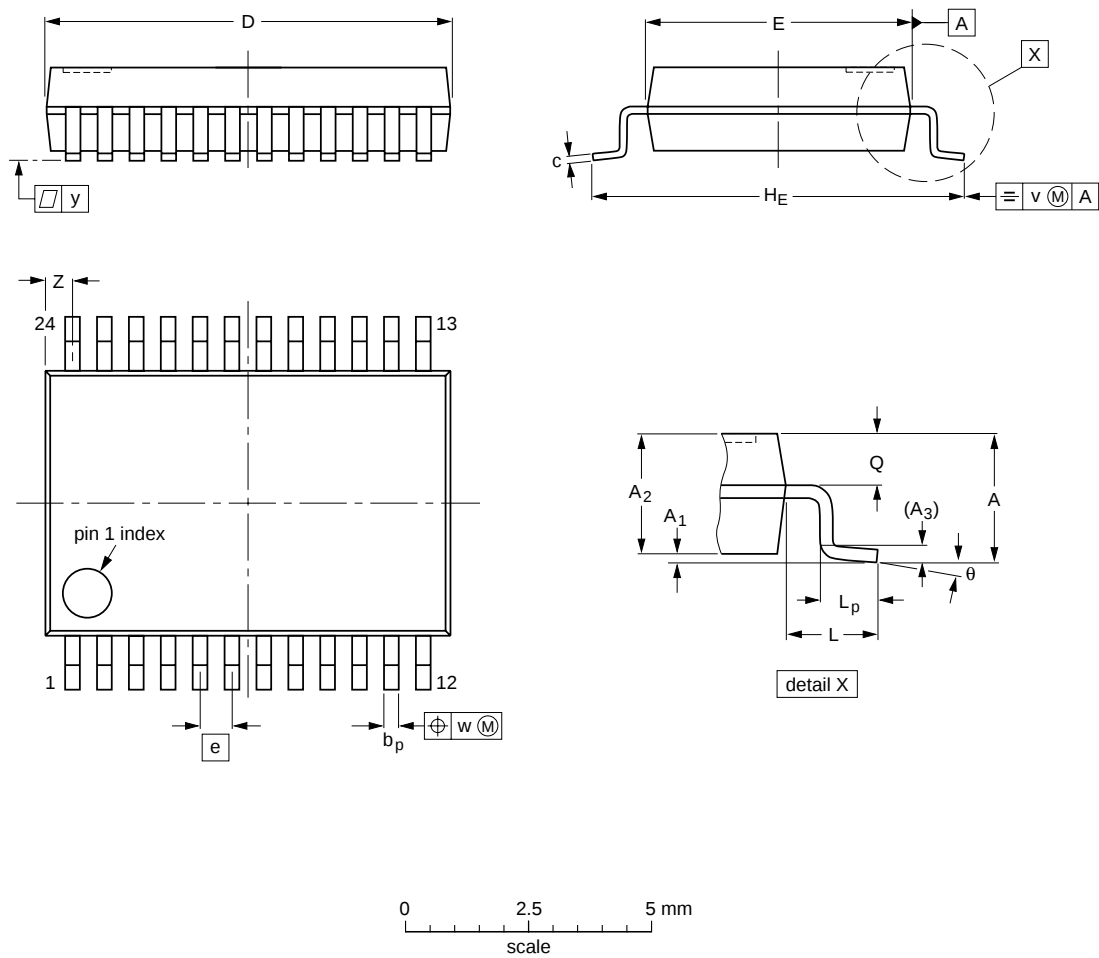
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				93-09-08- 95-02-04

Package information

Package outlines

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1

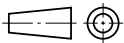


DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

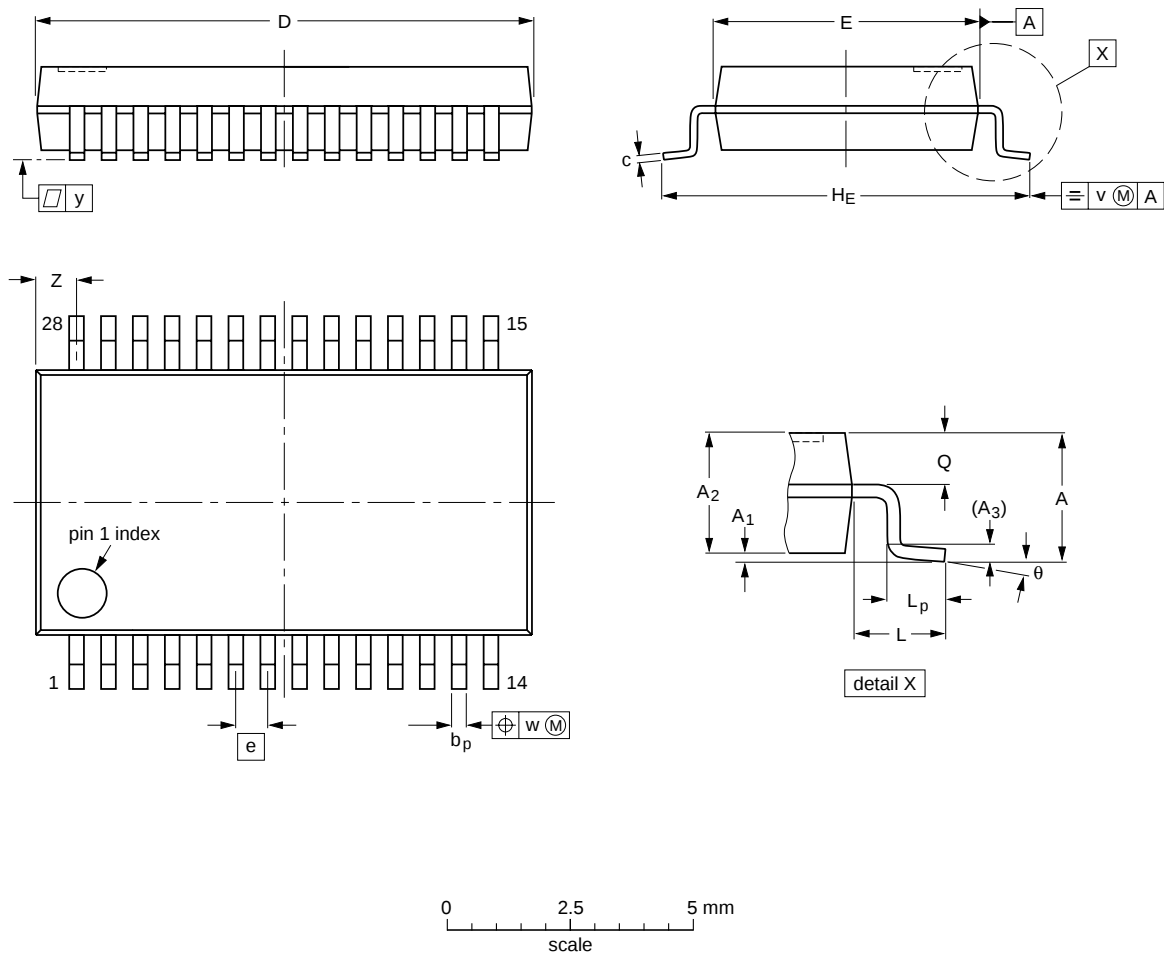
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT340-1		MO-150AG				93-09-08 95-02-04

Package information

Package outlines

SSOP28: plastic shrink small outline package; 28 leads; body width 5.3 mm

SOT341-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	10.4 10.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.1 0.7	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT341-1		MO-150AH				93-09-08- 95-02-04

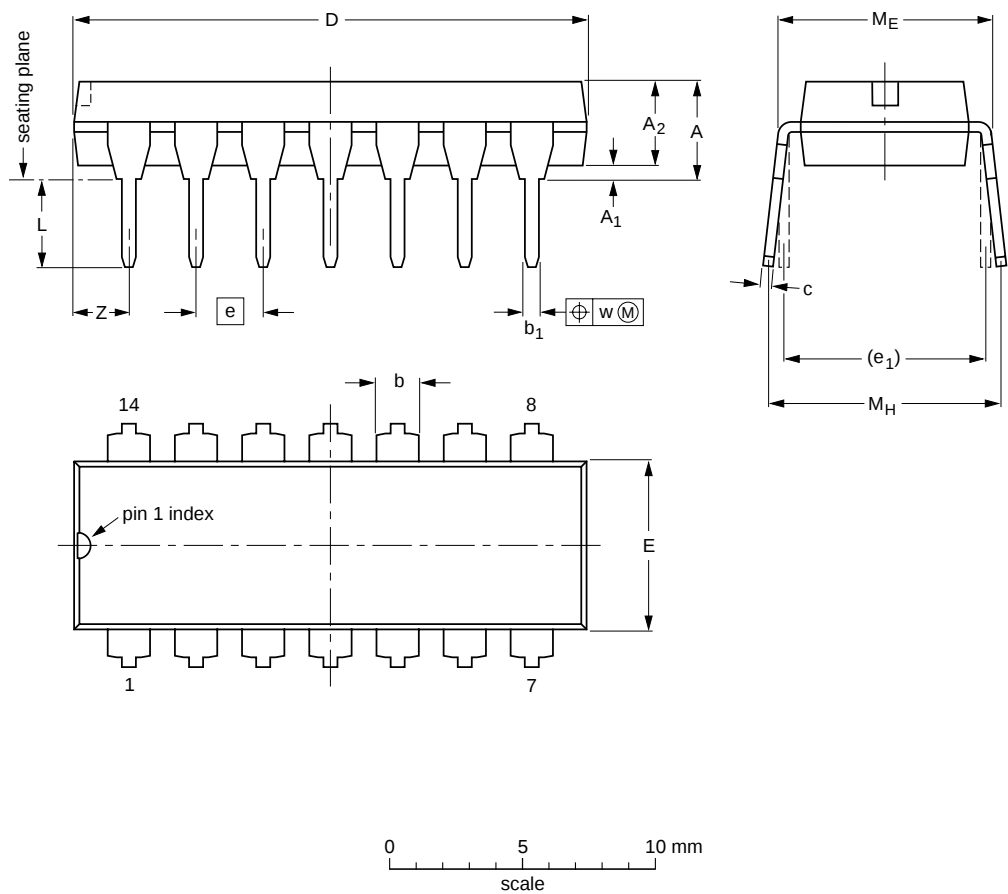
Package information

Package outlines

DIP

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

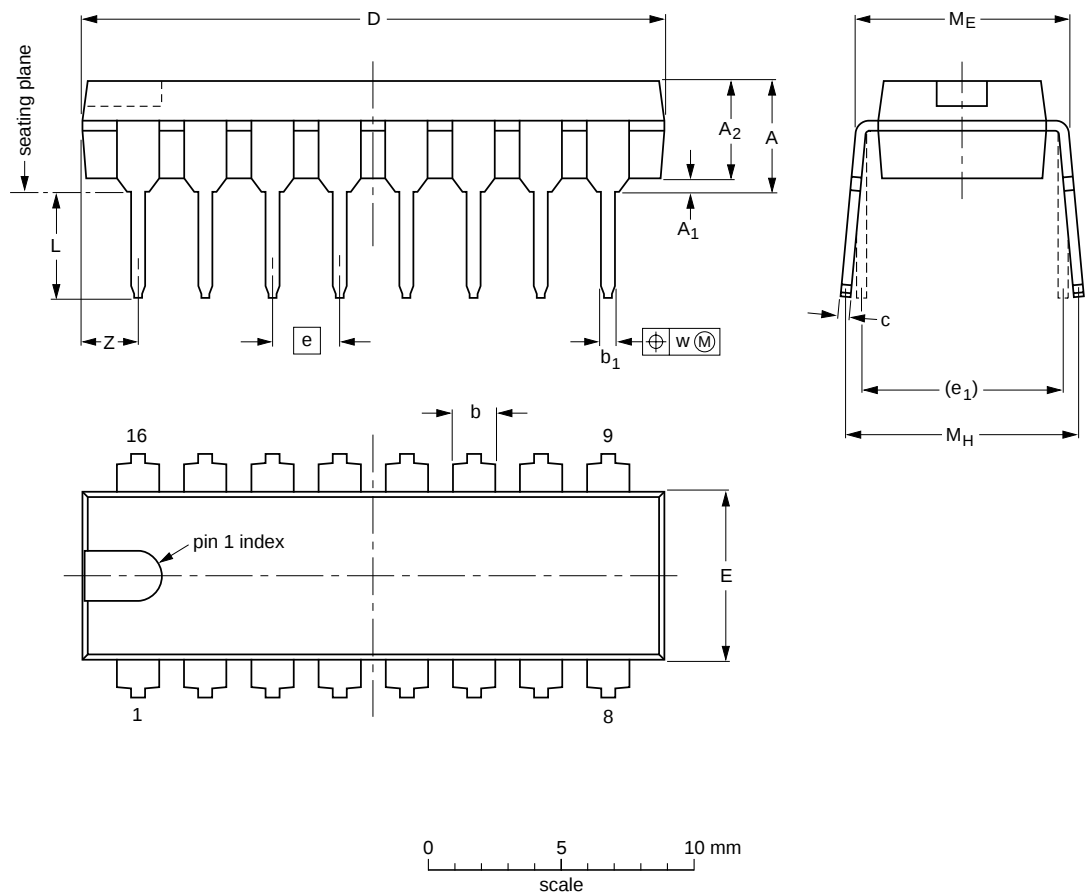
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11

Package information

Package outlines

DIP16: plastic dual in-line package; 16 leads (300 mil); long body

SOT38-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	2.2
inches	0.19	0.020	0.15	0.055 0.045	0.021 0.015	0.013 0.009	0.86 0.84	0.26 0.24	0.10	0.30	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

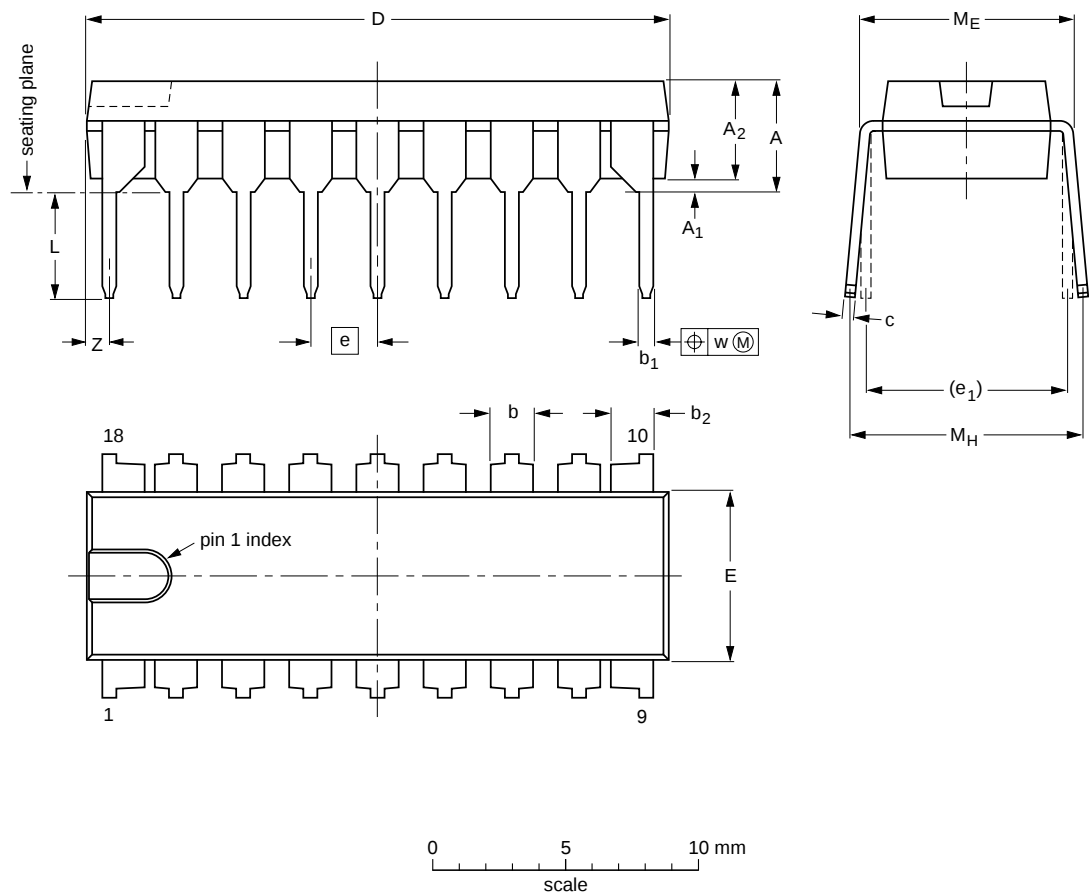
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-1	050G09	MO-001AE				92-10-02- 95-01-19

Package information

Package outlines

DIP18: plastic dual in-line package; 18 leads (300 mil)

SOT102-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	1.40 1.14	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	0.85
inches	0.19	0.020	0.15	0.055 0.044	0.021 0.015	0.055 0.044	0.013 0.009	0.86 0.84	0.26 0.24	0.10	0.30	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.033

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

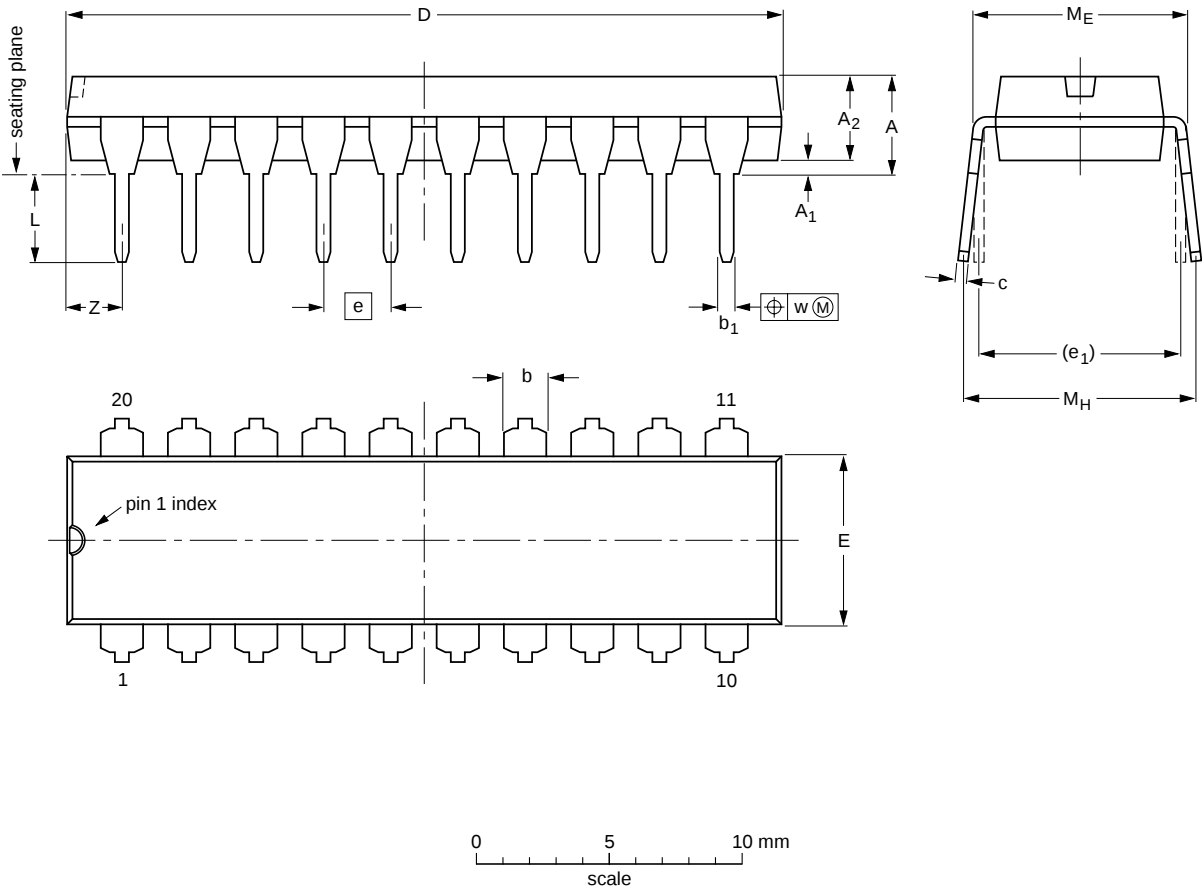
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT102-1						93-10-14 95-01-23

Package information

Package outlines

DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

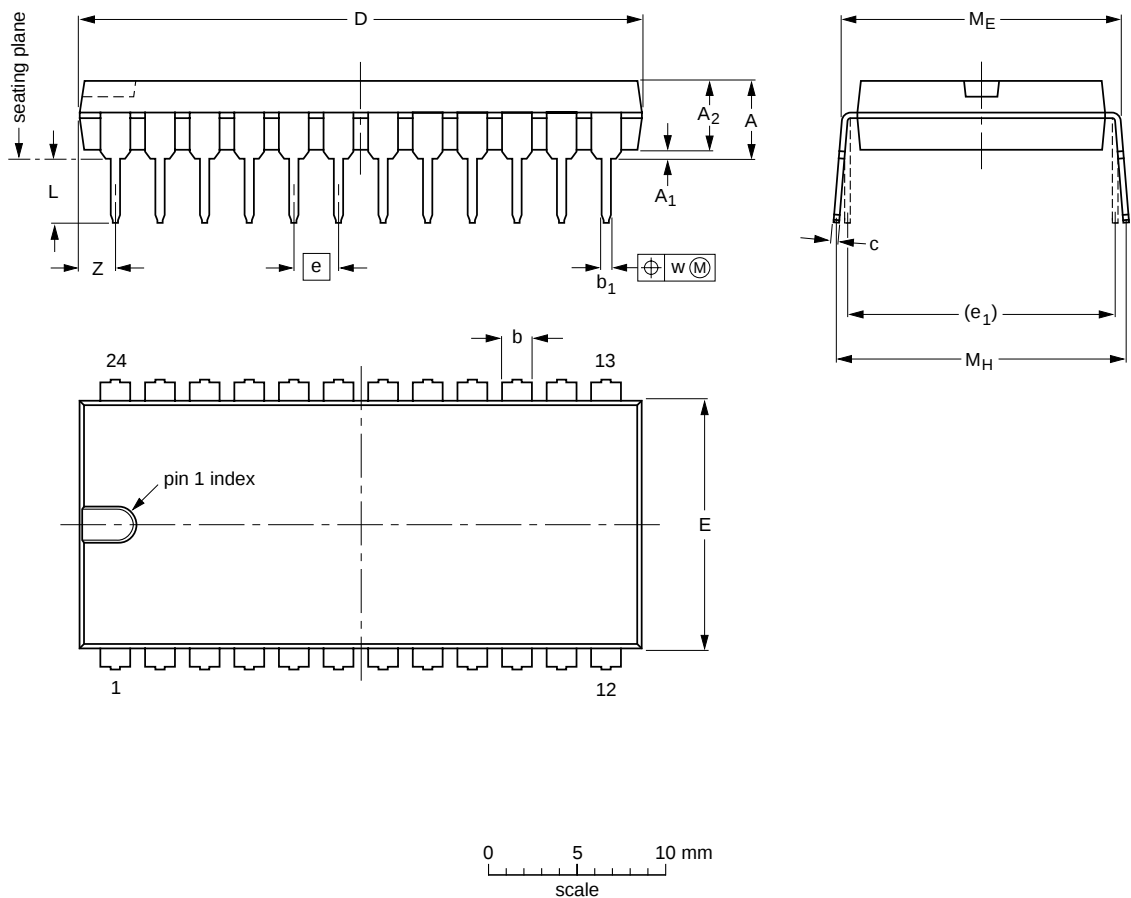
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			92-11-17 95-05-24

Package information

Package outlines

DIP24: plastic dual in-line package; 24 leads (600 mil)

SOT101-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	5.1	0.51	4.0	1.7 1.3	0.53 0.38	0.32 0.23	32.0 31.4	14.1 13.7	2.54	15.24	3.9 3.4	15.80 15.24	17.15 15.90	0.25	2.2
inches	0.20	0.020	0.16	0.066 0.051	0.021 0.015	0.013 0.009	1.26 1.24	0.56 0.54	0.10	0.60	0.15 0.13	0.62 0.60	0.68 0.63	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

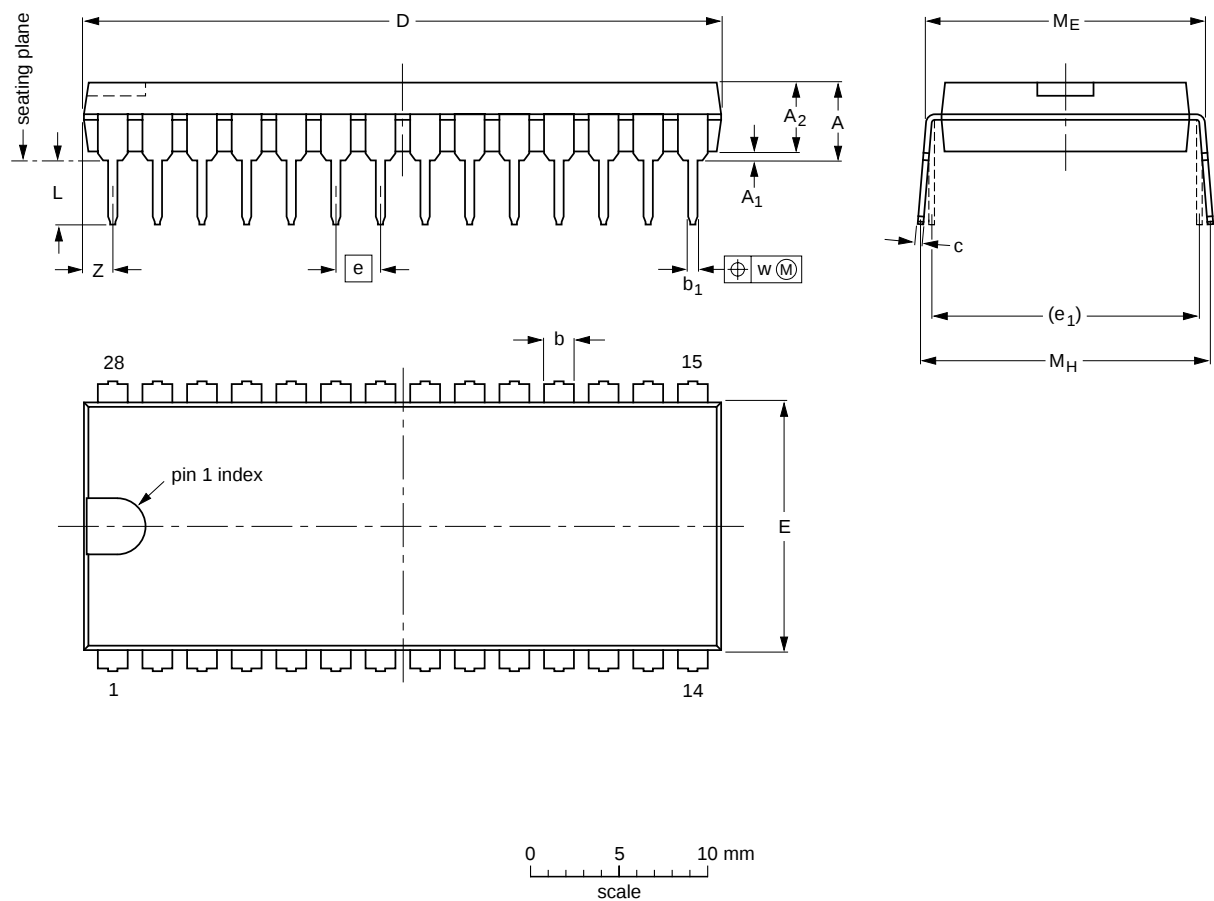
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT101-1	051G02	MO-015AD				92-11-17 95-01-23

Package information

Package outlines

DIP28: plastic dual in-line package; 28 leads (600 mil)

SOT117-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	5.1	0.51	4.0	1.7 1.3	0.53 0.38	0.32 0.23	36.0 35.0	14.1 13.7	2.54	15.24	3.9 3.4	15.80 15.24	17.15 15.90	0.25	1.7
inches	0.20	0.020	0.16	0.066 0.051	0.020 0.014	0.013 0.009	1.41 1.34	0.56 0.54	0.10	0.60	0.15 0.13	0.62 0.60	0.68 0.63	0.01	0.067

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

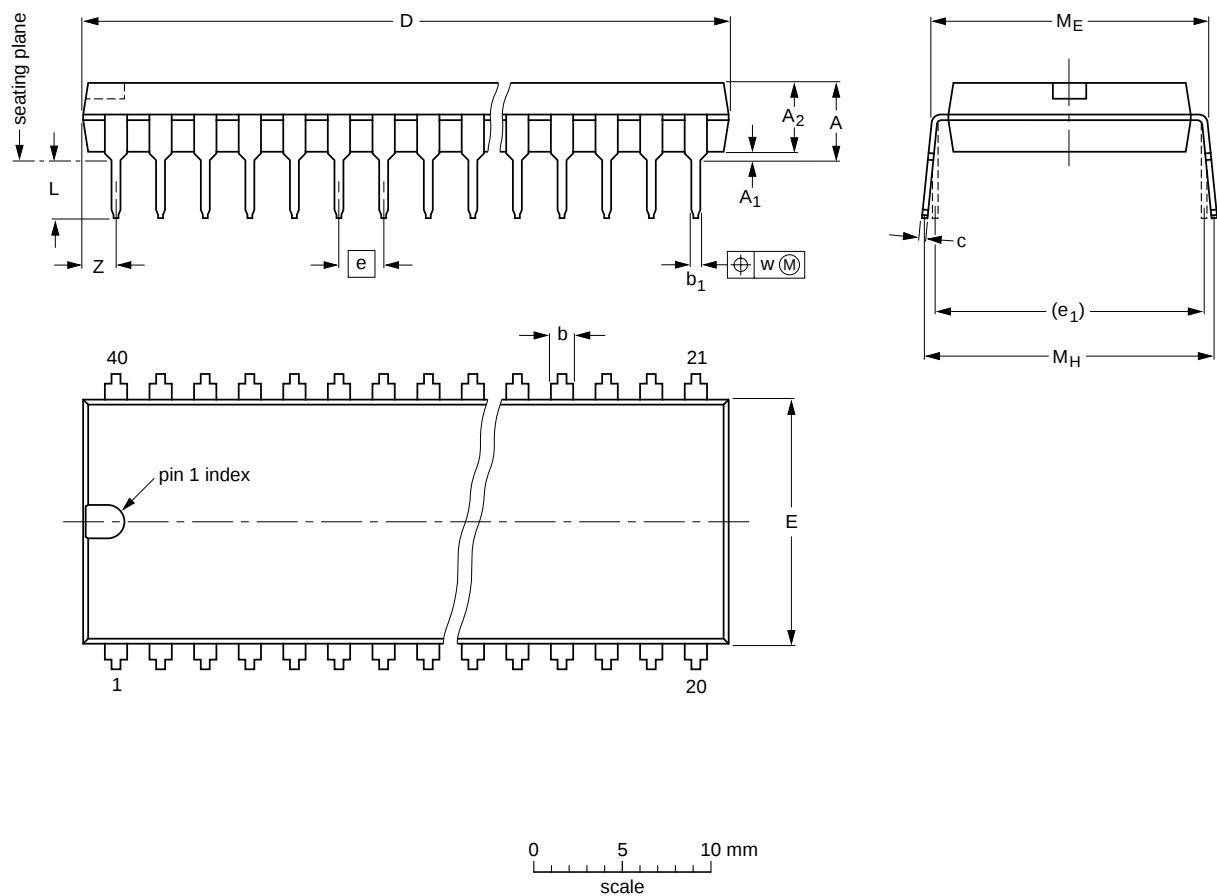
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT117-1	051G05	MO-015AH				92-11-17 95-01-14

Package information

Package outlines

DIP40: plastic dual in-line package; 40 leads (600 mil)

SOT129-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	z ⁽¹⁾ max.
mm	4.7	0.51	4.0	1.70 1.14	0.53 0.38	0.36 0.23	52.50 51.50	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.020	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.10	0.60	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

Note

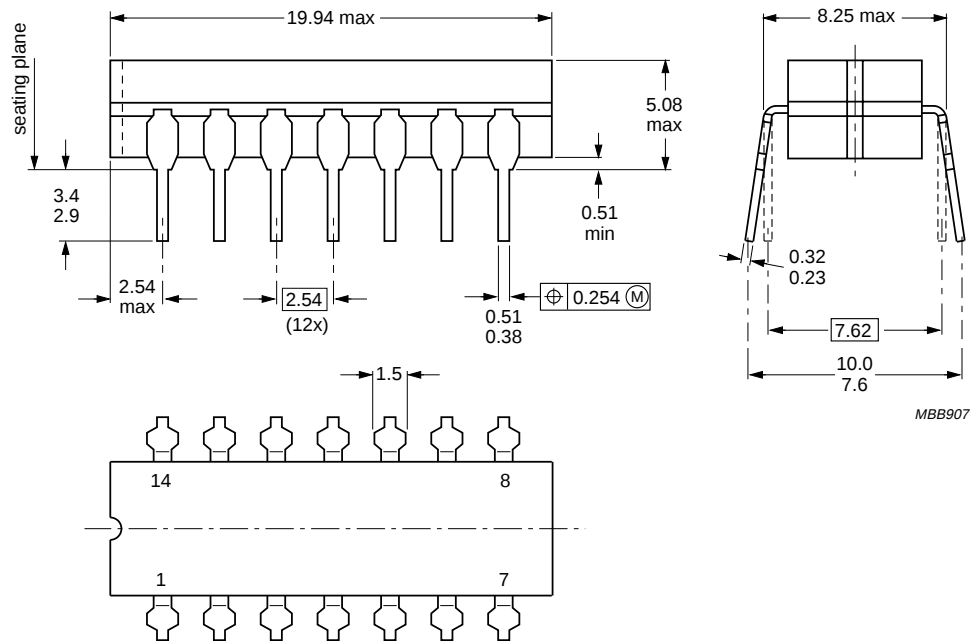
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT129-1	051G08	MO-015AJ				92-11-17 95-01-14

Package information

Package outlines

CDIP

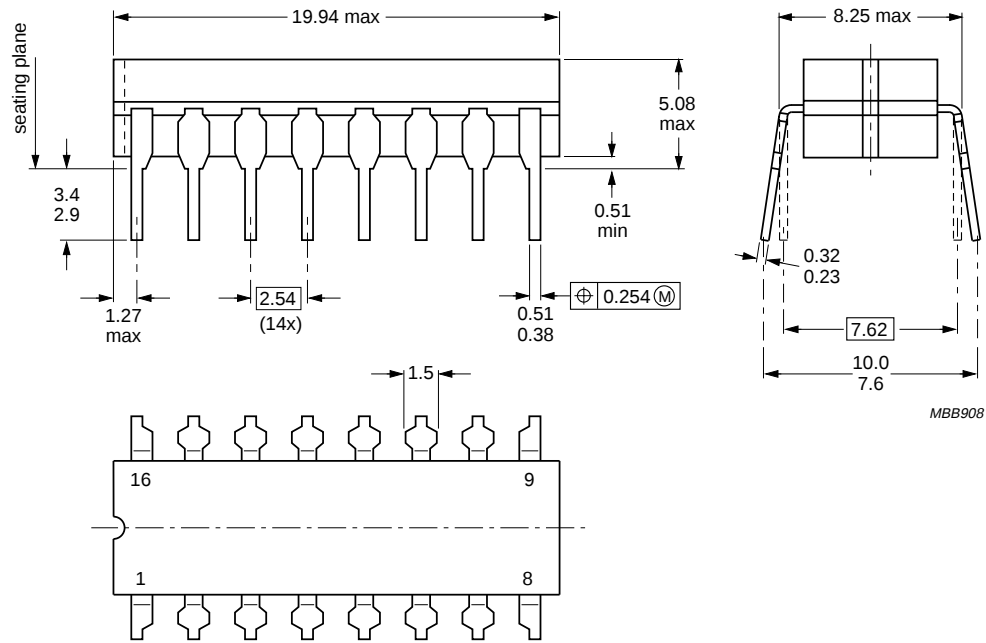


Dimensions in mm.

Ceramic dual in-line package; 14 leads; glass seal (CDIP14; SOT73-1).

Package information

Package outlines

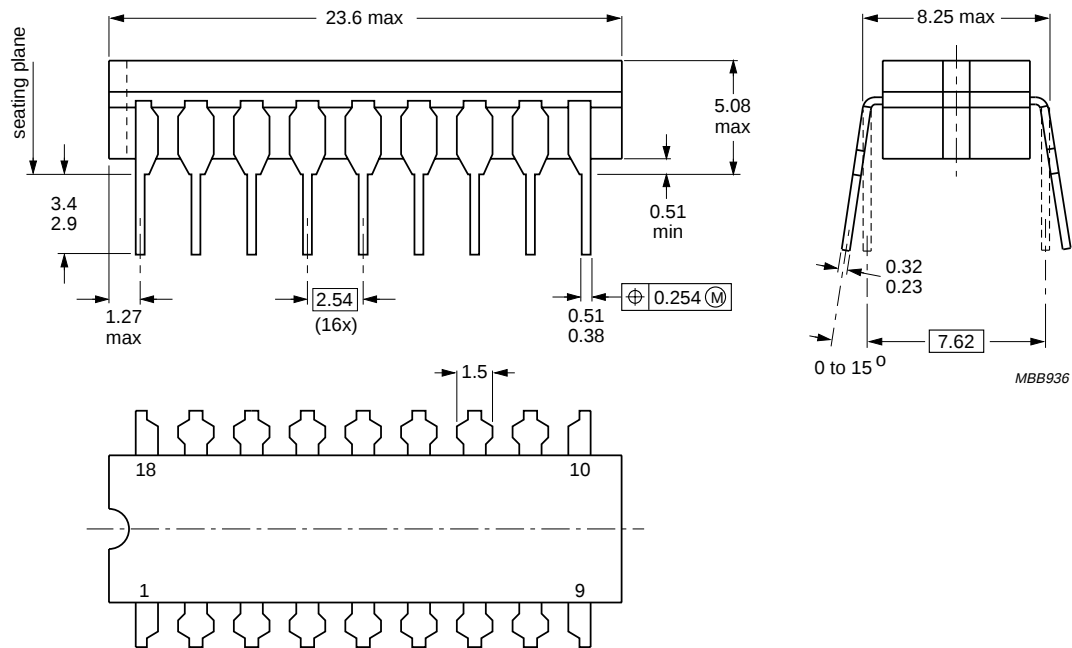


Dimensions in mm.

Ceramic dual in-line package; 16 leads; glass seal (CDIP16; SOT74-1).

Package information

Package outlines

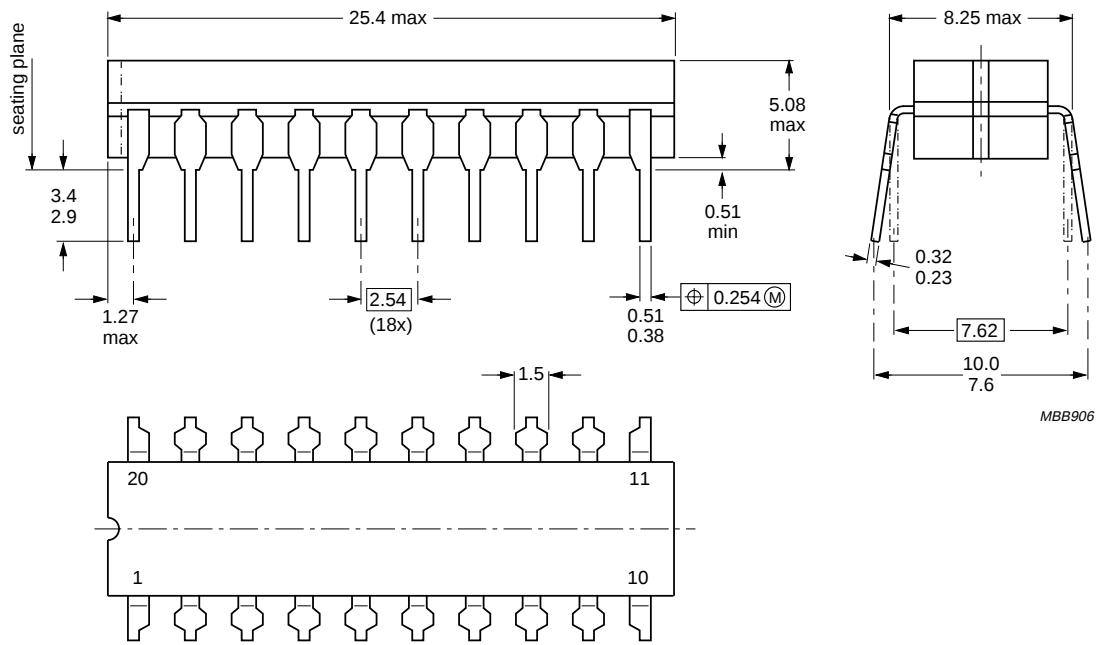


Dimensions in mm.

Ceramic dual in-line package; 18 leads; glass seal (CDIP18; SOT133-1).

Package information

Package outlines

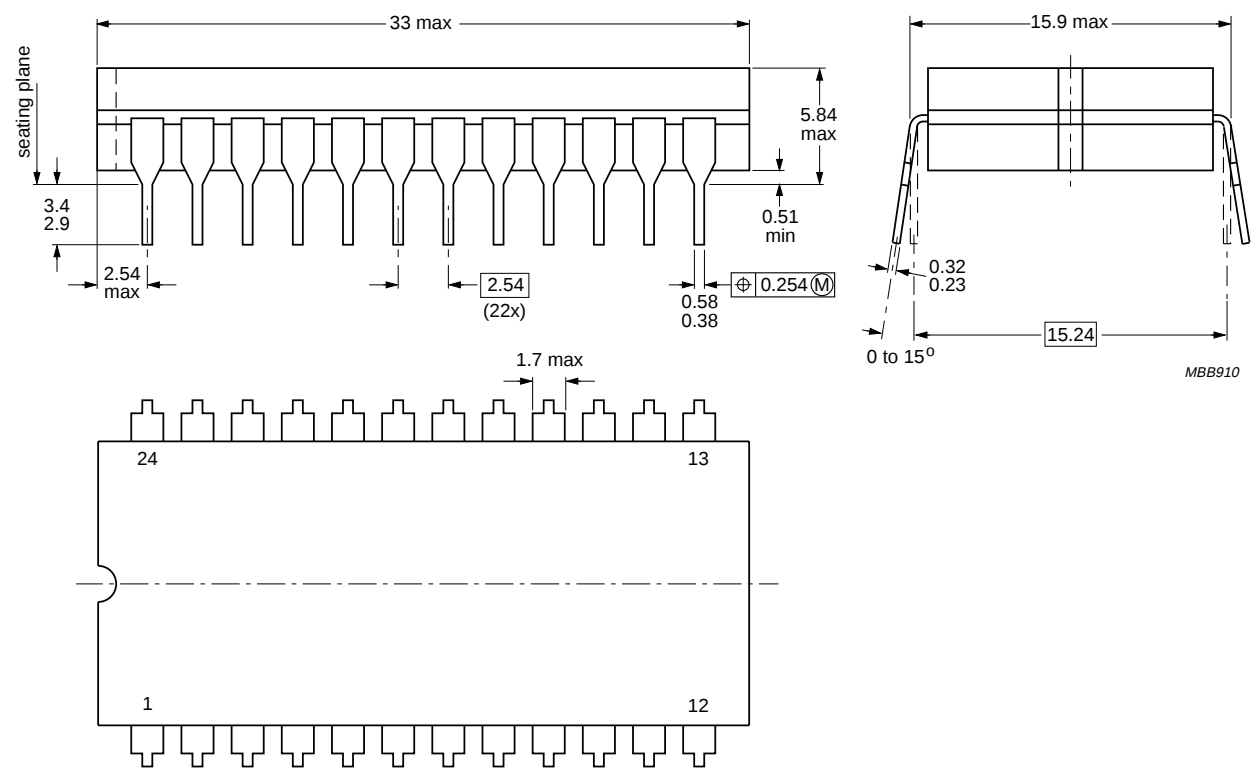


Dimensions in mm.

Ceramic dual in-line package; 20 leads; glass seal (CDIP20; SOT152-2).

Package information

Package outlines

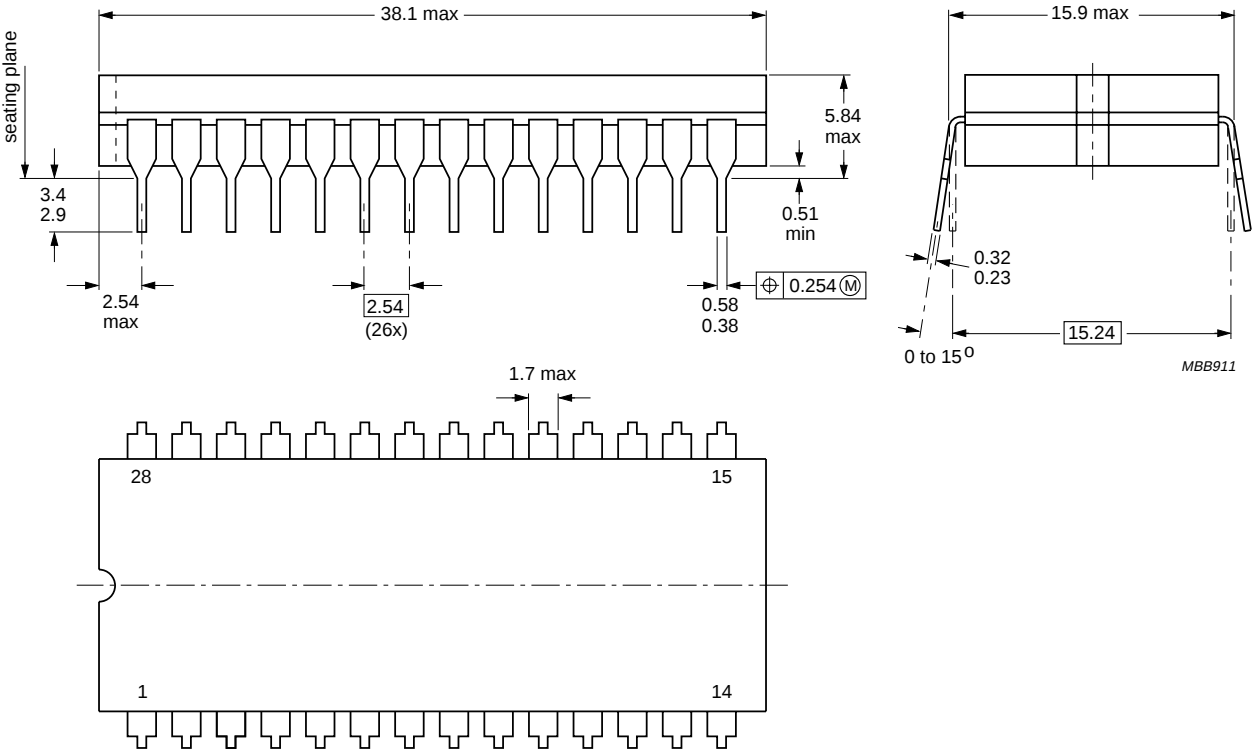


Dimensions in mm.

Ceramic dual in-line package; 24 leads; glass seal (CDIP24; SOT94-1).

Package information

Package outlines



Dimensions in mm.

Ceramic dual in-line package; 28 leads; glass seal (CDIP28; SOT135-1).